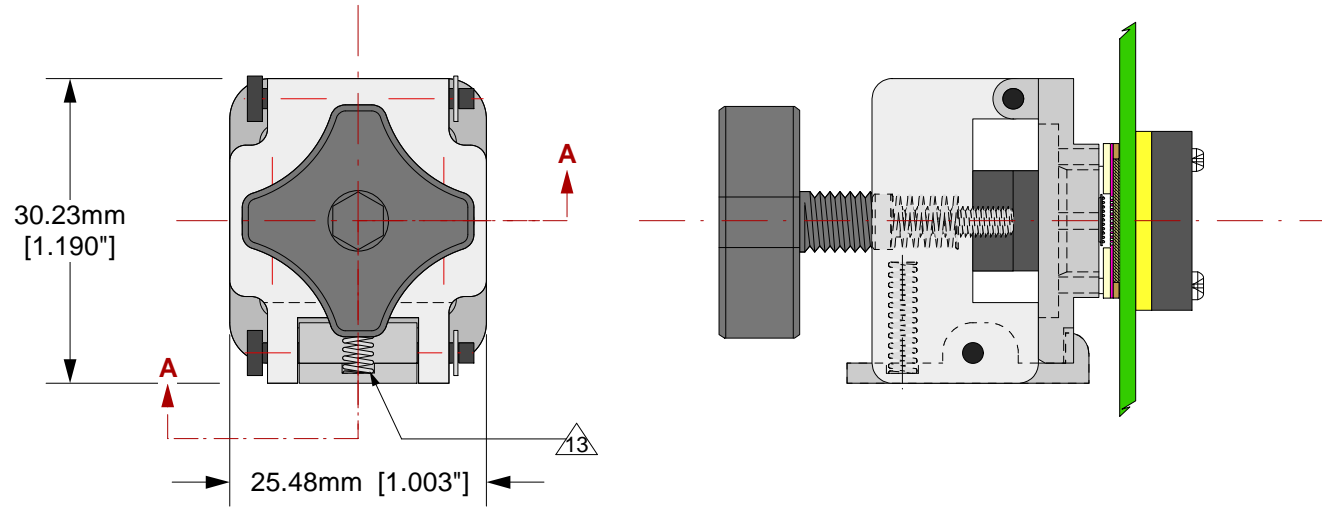
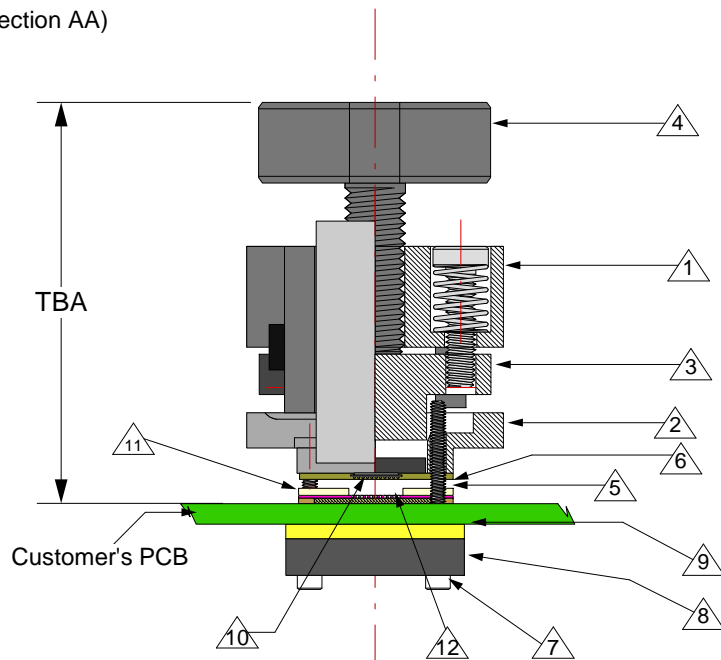


Top View



Side View  
(Section AA)




**Features**

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

**Materials:**

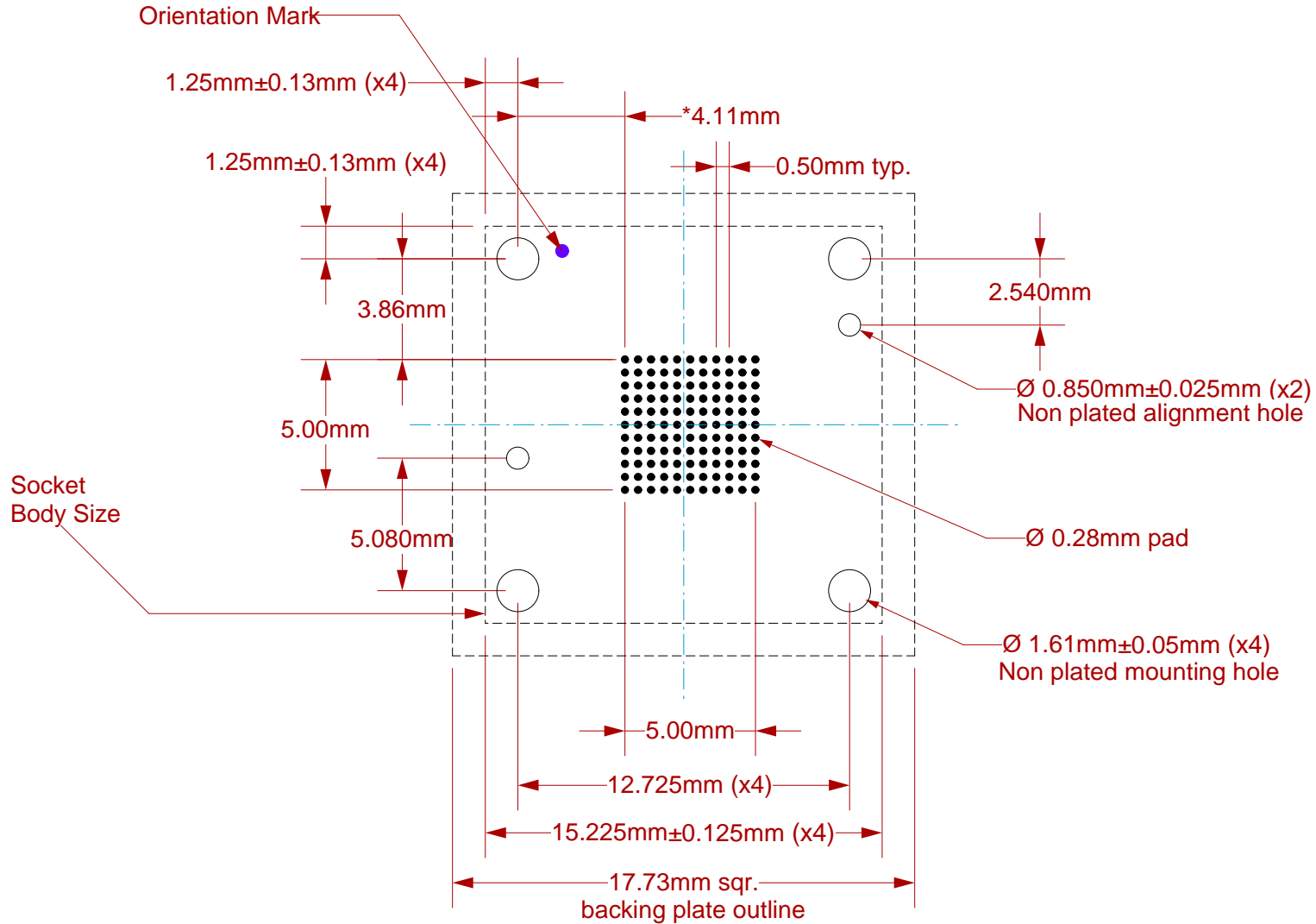
- 1 Clam Shell Lid: Black anodized Aluminum. Height = 16.5 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 8.5 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 25 mm, Fluted Knob
- 5 Ball Guide: Kapton polyimide.
- 6 IC Guide: Torlon
- 7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- 8 Backing Plate: Black anodized Aluminum. Thickness= 4mm
- 9 Insulation Plate: FR4/G10
- 10 Customer's BGA IC
- 11 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- 12 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 13 Latch: Black anodised Aluminum.

 <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<b>CG-BGA-5000 Drawing</b>	Status: Released	Scale: 1.33:1	Rev: B
	Drawing: J. Glab	Date: 3/14/07		
	File: CG-BGA-5000 Dwg.mcd	Modified: 07/16/14, DH		

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout  
Top View

**\*Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Target PCB Recommendations

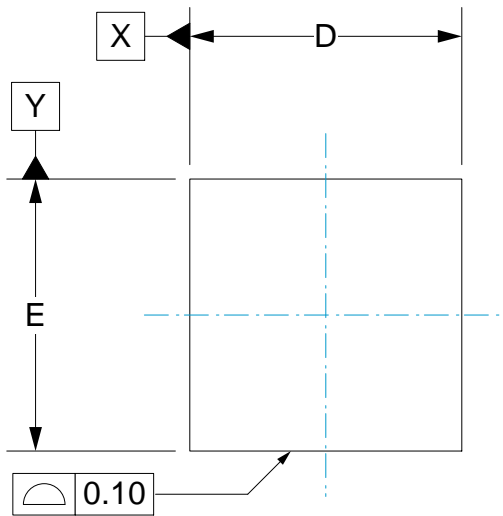
Total thickness: 1.6mm min.  
 Plating: Gold or Solder finish  
 PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

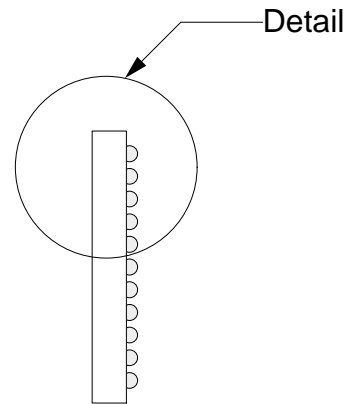
Recommended PCB Layout Tolerances:  $\pm 0.025\text{mm}$  [ $\pm 0.001''$ ] unless stated otherwise.

	<b>CG-BGA-5000 Drawing</b>		Status: Released	Scale: 4:1	Rev: B
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com		Drawing: J. Glab		Date: 3/14/07
			File: CG-BGA-5000 Dwg. mcd		Modified: 07/16/14, DH

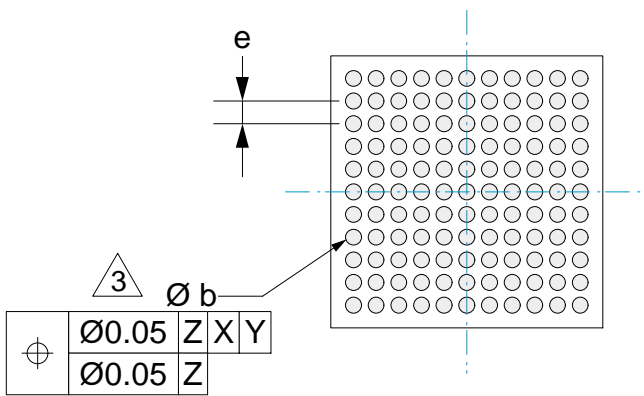
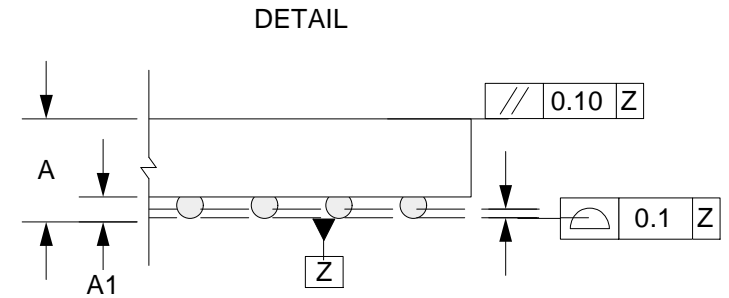
Recommended PCB Layout Tolerances:  $\pm 0.025\text{mm}$  [ $\pm 0.001''$ ] unless stated otherwise.



Top View



Side View




Bottom View

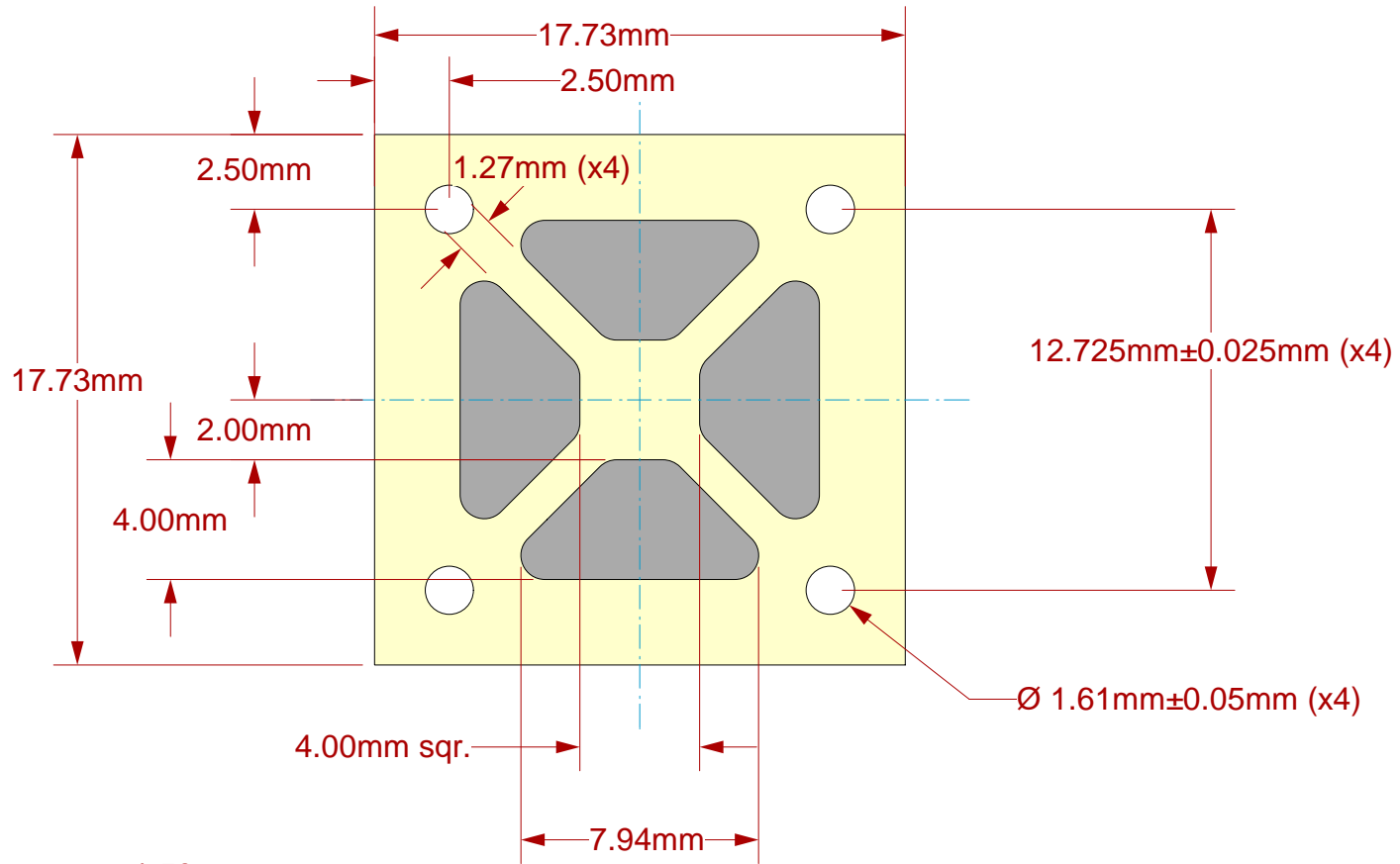
1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.0
A1	0.15	0.25
b		0.35
D	6.0 BSC	
E	6.0 BSC	
e	0.5 BSC	

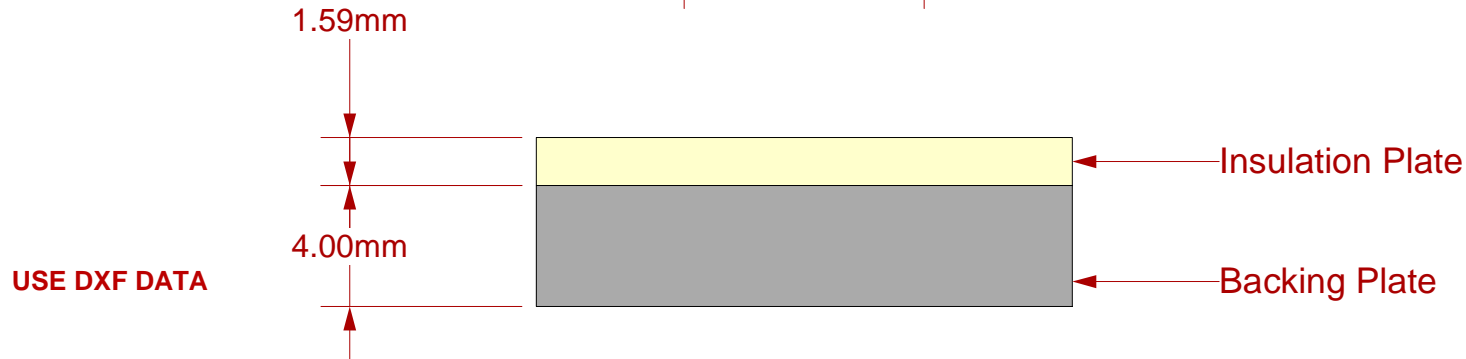
11 x 11 array

 <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p><b>CG-BGA-5000 Drawing</b></p>	<p>Status: Released</p>	<p>Scale: -</p>	<p>Rev: B</p>
	<p>Drawing: J. Glab</p>	<p>Date: 3/14/07</p>		
	<p>File: CG-BGA-5000 Dwg.mcd</p>	<p>Modified: 07/16/14, DH</p>		

Top View




Side View



Description: Backing Plate with Insulation Plate

PAGE 4 of 4

 <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p><b>CG-BGA-5000 Drawing</b></p>	<p>Status: Released</p>	<p>Scale: 4:1</p>	<p>Rev: B</p>
	<p>Drawing: J. Glab</p>	<p>Date: 3/14/07</p>		
	<p>File: CG-BGA-5000 Dwg.mcd</p>	<p>Modified: 07/16/14, DH</p>		

All dimensions are in mm.  
All tolerances are +/- 0.125mm.  
(Unless stated otherwise)

PAGE 4 of 4